

Bill of Materials

TIDA-00716

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number
1	2	C1, C5	1.0uF	Capacitor, Ceramic, 6.3V, X5R,10%	TDK	C1608X5R0J105K
2	4	C12, C13, C14, C15	2.2uF	Capacitor, Ceramic, 6.3V, X5R, 10%	TDK	C1608X5R0J225K
3	9	C2, C3, C4, C6, C7, C8, C9, C10, C11	10uF	Capacitor, Ceramic, 6.3V, X5R, 10%	TDK	C2012X5R0J106K
4	8	JP1, JP2, JP3, JP4, JP6, JP7, JP8, JP9		Header, 3 pin, 100mil spacing, (36-pin strip)	Sullins	PTC36SAAN
5	0	JP5	open	Header, 3 pin, 100mil spacing, (36-pin strip)	Sullins	PTC36SAAN
6	2	L2, L3**	2.2uH	Inductor, SMT, 1.72A, 59milliohm	TDK	VLCF4020T-2R2N1R7
7	1	L1**	3.3uH	Inductor, SMT, 1.52A, 78milliohm	TDK	VLCF4020T-3R3N1R5
8	0	Q1	open			
9	2	R1, R3	0	Resistor, Chip, 1/16W, 1%	Std	Std
10	2	R10, R11, R12, R13	182k	Resistor, Chip, 1/16W, 1%	Std	Std
11	1	R14	99k	Resistor, Chip, 1/16W, 1%	Std	Std
12	1	R15	20k	Resistor, Chip, 1/16W, 1%	Std	Std
13	1	R16	80k	Resistor, Chip, 1/16W, 1%	Std	Std
14	1	R17	100k	Resistor, Chip, 1/16W, 1%	Std	Std
15	2	R18	150k	Resistor, Chip, 1/16W, 1%	Std	Std
16	0	R2	Open	Resistor, Chip, 1/16W, 1%		
17	1	R4	1	Resistor, Chip, 1/16W, 5%	Std	Std
18	1	R5	1.21M	Resistor, Chip, 1/16W, 1%	Std	Std
19	1	R6	499k	Resistor, Chip, 1/16W, 1%	Std	Std
20	0	R7, R8	open	Resistor, Chip, 1/16W, 1%		
21	2	R9, R19	100k	Resistor, Chip, 1/16W, 1%	Std	Std
22	1	U1**	TPS650250RHB	IC, Power Management ICs for Li-Ion Powered Systems	TI	TPS650250RHB
23	1			PCB, 2.2 ln x 3.3 ln x 0.064 ln	Any	HPA447

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